

Case: AMKOR-015A



2811#3
S.I
0424.02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECEIVED
MAR - 1 2002
TC-2800 MAIL ROOM

Applicant:	Jong Sik Paek)	
)	Art Unit: 2811
Serial No.:	10/034,656)	
)	Examiner: Unknown
Filed:	12/26/2001)	
)	
For:	SEMICONDUCTOR PACKAGE)	
	INCLUDING FLIP CHIP)	

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. SECTION 1.97

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir/Madam:

Pursuant to 37 C.F.R. § 1.97, the following Information Disclosure Statement is submitted as listed on form PTO-1449 enclosed herewith in duplicate. Copies of all disclosure documents are attached hereto for the Examiner's review.

No representation is made that the references disclosed herein legally constitute prior art, or that more relevant references are not available. The disclosure documents enclosed herewith and listed on the attached form (PTO-1449) are printed in the English language and/or accompanied by an Abstract published in the English language.

The references listed herein, when taken alone or in combination are not believed to disclose nor make obvious the invention as claimed in the subject application.

As this Information Disclosure Statement is being submitted before the stipulated three

months from the filing date of the application and/or before the mailing of a first Office Action,
it is believed that no fee is required. If a fee is required, please charge Account Number 19-4330.

Respectfully submitted,

Dated: 2/15/02
Customer No. 007663

By:



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